

# Global Packaging Materials for IGBT and SiC Modules Market 2024 by Company, Regions, Type and Application, Forecast to 2030

https://marketpublishers.com/r/G93D239D5273EN.html

Date: April 2024 Pages: 127 Price: US\$ 3,480.00 (Single User License) ID: G93D239D5273EN

# **Abstracts**

This report studies the Power Module Packaging Materials, include Encapsulation (Silicone Gel and Epoxy), Die Attach (soldering, sintering), ceramic substrates (DBC and AMB), Baseplate (copper, ALSiC, Thermal Interface Materials (crease, PCM), Electrical Interconnection (aluminum-based and copper-based).

According to our (Global Info Research) latest study, the global Packaging Materials for IGBT and SiC Modules market size was valued at US\$ 2350 million in 2023 and is forecast to a readjusted size of USD 3719 million by 2030 with a CAGR of 6.4% during review period.

This report is a detailed and comprehensive analysis for global Packaging Materials for IGBT and SiC Modules market. Both quantitative and qualitative analyses are presented by company, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2024, are provided.

Key Features:

Global Packaging Materials for IGBT and SiC Modules market size and forecasts, in consumption value (\$ Million), 2019-2030

Global Packaging Materials for IGBT and SiC Modules market size and forecasts by region and country, in consumption value (\$ Million), 2019-2030



Global Packaging Materials for IGBT and SiC Modules market size and forecasts, by Type and by Application, in consumption value (\$ Million), 2019-2030

Global Packaging Materials for IGBT and SiC Modules market shares of main players, in revenue (\$ Million), 2019-2024

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries

To assess the growth potential for Packaging Materials for IGBT and SiC Modules

To forecast future growth in each product and end-use market

To assess competitive factors affecting the marketplace

This report profiles key players in the global Packaging Materials for IGBT and SiC Modules market based on the following parameters - company overview, revenue, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Rogers Corporation, MacDermid Alpha, 3M, Dow, Indium Corporation, Heraeus, Henkel, Ferrotec, Kyocera, NGK Electronics Devices, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

#### Market segmentation

Packaging Materials for IGBT and SiC Modules market is split by Type and by Application. For the period 2019-2030, the growth among segments provides accurate calculations and forecasts for Consumption Value by Type and by Application. This analysis can help you expand your business by targeting qualified niche markets.

#### Market segmentation

Packaging Materials for IGBT and SiC Modules market is split by Type and by Application. For the period 2018-2029, the growth among segments provides accurate calculations and forecasts for Consumption Value by Type and by Application. This



analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

Encapsulation (Silicone Gel and Epoxy)

????

Ceramic Substrate

Thermal Interface Materials

**Electrical Interconnection** 

Others

Market segment by Application

Automotive

**Traction & Railway** 

PV, Wind Power & Power Grid

Industrial Motor

Home Appliances

USP

Other

Market segment by players, this report covers

**Rogers Corporation** 

MacDermid Alpha

Global Packaging Materials for IGBT and SiC Modules Market 2024 by Company, Regions, Type and Application, For...



3M

Dow

Indium Corporation

Heraeus

Henkel

Ferrotec

Kyocera

NGK Electronics Devices

Dowa

Denka

Tanaka

Resonac

BYD

**Toshiba Materials** 

KCC

Shengda Tech

Nanjing Zhongjiang New Material Science & Technology

Market segment by regions, regional analysis covers

North America (United States, Canada and Mexico)



Europe (Germany, France, UK, Russia, Italy and Rest of Europe)

Asia-Pacific (China, Japan, South Korea, India, Southeast Asia and Rest of Asia-Pacific)

South America (Brazil, Rest of South America)

Middle East & Africa (Turkey, Saudi Arabia, UAE, Rest of Middle East & Africa)

The content of the study subjects, includes a total of 13 chapters:

Chapter 1, to describe Packaging Materials for IGBT and SiC Modules product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top players of Packaging Materials for IGBT and SiC Modules, with revenue, gross margin, and global market share of Packaging Materials for IGBT and SiC Modules from 2019 to 2024.

Chapter 3, the Packaging Materials for IGBT and SiC Modules competitive situation, revenue, and global market share of top players are analyzed emphatically by landscape contrast.

Chapter 4 and 5, to segment the market size by Type and by Application, with consumption value and growth rate by Type, by Application, from 2019 to 2030.

Chapter 6, 7, 8, 9, and 10, to break the market size data at the country level, with revenue and market share for key countries in the world, from 2019 to 2024.and Packaging Materials for IGBT and SiC Modules market forecast, by regions, by Type and by Application, with consumption value, from 2024 to 2030.

Chapter 11, market dynamics, drivers, restraints, trends, Porters Five Forces analysis.

Chapter 12, the key raw materials and key suppliers, and industry chain of Packaging Materials for IGBT and SiC Modules.

Chapter 13, to describe Packaging Materials for IGBT and SiC Modules research findings and conclusion.

Global Packaging Materials for IGBT and SiC Modules Market 2024 by Company, Regions, Type and Application, For...



# Contents

#### **1 MARKET OVERVIEW**

- 1.1 Product Overview and Scope
- 1.2 Market Estimation Caveats and Base Year
- 1.3 Classification of Packaging Materials for IGBT and SiC Modules by Type
- 1.3.1 Overview: Global Packaging Materials for IGBT and SiC Modules Market Size by Type: 2019 Versus 2023 Versus 2030
- 1.3.2 Global Packaging Materials for IGBT and SiC Modules Consumption Value Market Share by Type in 2023
  - 1.3.3 Encapsulation (Silicone Gel and Epoxy)
  - 1.3.4 ????
  - 1.3.5 Ceramic Substrate
  - 1.3.6 Thermal Interface Materials
  - 1.3.7 Electrical Interconnection
  - 1.3.8 Others

1.4 Global Packaging Materials for IGBT and SiC Modules Market by Application

1.4.1 Overview: Global Packaging Materials for IGBT and SiC Modules Market Size by Application: 2019 Versus 2023 Versus 2030

- 1.4.2 Automotive
- 1.4.3 Traction & Railway
- 1.4.4 PV, Wind Power & Power Grid
- 1.4.5 Industrial Motor
- 1.4.6 Home Appliances
- 1.4.7 USP
- 1.4.8 Other

1.5 Global Packaging Materials for IGBT and SiC Modules Market Size & Forecast

1.6 Global Packaging Materials for IGBT and SiC Modules Market Size and Forecast by Region

1.6.1 Global Packaging Materials for IGBT and SiC Modules Market Size by Region: 2019 VS 2023 VS 2030

1.6.2 Global Packaging Materials for IGBT and SiC Modules Market Size by Region, (2019-2030)

1.6.3 North America Packaging Materials for IGBT and SiC Modules Market Size and Prospect (2019-2030)

1.6.4 Europe Packaging Materials for IGBT and SiC Modules Market Size and Prospect (2019-2030)

1.6.5 Asia-Pacific Packaging Materials for IGBT and SiC Modules Market Size and



Prospect (2019-2030)

1.6.6 South America Packaging Materials for IGBT and SiC Modules Market Size and Prospect (2019-2030)

1.6.7 Middle East & Africa Packaging Materials for IGBT and SiC Modules Market Size and Prospect (2019-2030)

### 2 COMPANY PROFILES

- 2.1 Rogers Corporation
- 2.1.1 Rogers Corporation Details
- 2.1.2 Rogers Corporation Major Business

2.1.3 Rogers Corporation Packaging Materials for IGBT and SiC Modules Product and Solutions

2.1.4 Rogers Corporation Packaging Materials for IGBT and SiC Modules Revenue, Gross Margin and Market Share (2019-2024)

- 2.1.5 Rogers Corporation Recent Developments and Future Plans
- 2.2 MacDermid Alpha
  - 2.2.1 MacDermid Alpha Details
  - 2.2.2 MacDermid Alpha Major Business
- 2.2.3 MacDermid Alpha Packaging Materials for IGBT and SiC Modules Product and Solutions

2.2.4 MacDermid Alpha Packaging Materials for IGBT and SiC Modules Revenue, Gross Margin and Market Share (2019-2024)

2.2.5 MacDermid Alpha Recent Developments and Future Plans

2.3 3M

2.3.1 3M Details

2.3.2 3M Major Business

2.3.3 3M Packaging Materials for IGBT and SiC Modules Product and Solutions

2.3.4 3M Packaging Materials for IGBT and SiC Modules Revenue, Gross Margin and Market Share (2019-2024)

2.3.5 3M Recent Developments and Future Plans

2.4 Dow

- 2.4.1 Dow Details
- 2.4.2 Dow Major Business
- 2.4.3 Dow Packaging Materials for IGBT and SiC Modules Product and Solutions

2.4.4 Dow Packaging Materials for IGBT and SiC Modules Revenue, Gross Margin and Market Share (2019-2024)

2.4.5 Dow Recent Developments and Future Plans

2.5 Indium Corporation



2.5.1 Indium Corporation Details

2.5.2 Indium Corporation Major Business

2.5.3 Indium Corporation Packaging Materials for IGBT and SiC Modules Product and Solutions

2.5.4 Indium Corporation Packaging Materials for IGBT and SiC Modules Revenue, Gross Margin and Market Share (2019-2024)

2.5.5 Indium Corporation Recent Developments and Future Plans

2.6 Heraeus

2.6.1 Heraeus Details

2.6.2 Heraeus Major Business

2.6.3 Heraeus Packaging Materials for IGBT and SiC Modules Product and Solutions

2.6.4 Heraeus Packaging Materials for IGBT and SiC Modules Revenue, Gross Margin and Market Share (2019-2024)

2.6.5 Heraeus Recent Developments and Future Plans

2.7 Henkel

2.7.1 Henkel Details

2.7.2 Henkel Major Business

2.7.3 Henkel Packaging Materials for IGBT and SiC Modules Product and Solutions

2.7.4 Henkel Packaging Materials for IGBT and SiC Modules Revenue, Gross Margin and Market Share (2019-2024)

2.7.5 Henkel Recent Developments and Future Plans

2.8 Ferrotec

2.8.1 Ferrotec Details

2.8.2 Ferrotec Major Business

2.8.3 Ferrotec Packaging Materials for IGBT and SiC Modules Product and Solutions

2.8.4 Ferrotec Packaging Materials for IGBT and SiC Modules Revenue, Gross Margin and Market Share (2019-2024)

2.8.5 Ferrotec Recent Developments and Future Plans

2.9 Kyocera

2.9.1 Kyocera Details

2.9.2 Kyocera Major Business

2.9.3 Kyocera Packaging Materials for IGBT and SiC Modules Product and Solutions

2.9.4 Kyocera Packaging Materials for IGBT and SiC Modules Revenue, Gross Margin and Market Share (2019-2024)

2.9.5 Kyocera Recent Developments and Future Plans

2.10 NGK Electronics Devices

2.10.1 NGK Electronics Devices Details

2.10.2 NGK Electronics Devices Major Business

2.10.3 NGK Electronics Devices Packaging Materials for IGBT and SiC Modules



Product and Solutions

2.10.4 NGK Electronics Devices Packaging Materials for IGBT and SiC Modules Revenue, Gross Margin and Market Share (2019-2024)

2.10.5 NGK Electronics Devices Recent Developments and Future Plans

2.11 Dowa

2.11.1 Dowa Details

2.11.2 Dowa Major Business

2.11.3 Dowa Packaging Materials for IGBT and SiC Modules Product and Solutions

2.11.4 Dowa Packaging Materials for IGBT and SiC Modules Revenue, Gross Margin and Market Share (2019-2024)

2.11.5 Dowa Recent Developments and Future Plans

2.12 Denka

2.12.1 Denka Details

- 2.12.2 Denka Major Business
- 2.12.3 Denka Packaging Materials for IGBT and SiC Modules Product and Solutions

2.12.4 Denka Packaging Materials for IGBT and SiC Modules Revenue, Gross Margin and Market Share (2019-2024)

2.12.5 Denka Recent Developments and Future Plans

2.13 Tanaka

2.13.1 Tanaka Details

- 2.13.2 Tanaka Major Business
- 2.13.3 Tanaka Packaging Materials for IGBT and SiC Modules Product and Solutions

2.13.4 Tanaka Packaging Materials for IGBT and SiC Modules Revenue, Gross Margin and Market Share (2019-2024)

2.13.5 Tanaka Recent Developments and Future Plans

2.14 Resonac

2.14.1 Resonac Details

2.14.2 Resonac Major Business

2.14.3 Resonac Packaging Materials for IGBT and SiC Modules Product and Solutions

2.14.4 Resonac Packaging Materials for IGBT and SiC Modules Revenue, Gross

Margin and Market Share (2019-2024)

2.14.5 Resonac Recent Developments and Future Plans

2.15 BYD

2.15.1 BYD Details

2.15.2 BYD Major Business

2.15.3 BYD Packaging Materials for IGBT and SiC Modules Product and Solutions

2.15.4 BYD Packaging Materials for IGBT and SiC Modules Revenue, Gross Margin and Market Share (2019-2024)

2.15.5 BYD Recent Developments and Future Plans



2.16 Toshiba Materials

2.16.1 Toshiba Materials Details

2.16.2 Toshiba Materials Major Business

2.16.3 Toshiba Materials Packaging Materials for IGBT and SiC Modules Product and Solutions

2.16.4 Toshiba Materials Packaging Materials for IGBT and SiC Modules Revenue, Gross Margin and Market Share (2019-2024)

2.16.5 Toshiba Materials Recent Developments and Future Plans

2.17 KCC

2.17.1 KCC Details

2.17.2 KCC Major Business

2.17.3 KCC Packaging Materials for IGBT and SiC Modules Product and Solutions

2.17.4 KCC Packaging Materials for IGBT and SiC Modules Revenue, Gross Margin and Market Share (2019-2024)

2.17.5 KCC Recent Developments and Future Plans

2.18 Shengda Tech

2.18.1 Shengda Tech Details

2.18.2 Shengda Tech Major Business

2.18.3 Shengda Tech Packaging Materials for IGBT and SiC Modules Product and Solutions

2.18.4 Shengda Tech Packaging Materials for IGBT and SiC Modules Revenue, Gross Margin and Market Share (2019-2024)

2.18.5 Shengda Tech Recent Developments and Future Plans

2.19 Nanjing Zhongjiang New Material Science & Technology

2.19.1 Nanjing Zhongjiang New Material Science & Technology Details

2.19.2 Nanjing Zhongjiang New Material Science & Technology Major Business

2.19.3 Nanjing Zhongjiang New Material Science & Technology Packaging Materials for IGBT and SiC Modules Product and Solutions

2.19.4 Nanjing Zhongjiang New Material Science & Technology Packaging Materials for IGBT and SiC Modules Revenue, Gross Margin and Market Share (2019-2024)

2.19.5 Nanjing Zhongjiang New Material Science & Technology Recent Developments and Future Plans

# **3 MARKET COMPETITION, BY PLAYERS**

3.1 Global Packaging Materials for IGBT and SiC Modules Revenue and Share by Players (2019-2024)

3.2 Market Share Analysis (2023)

3.2.1 Market Share of Packaging Materials for IGBT and SiC Modules by Company



Revenue

3.2.2 Top 3 Packaging Materials for IGBT and SiC Modules Players Market Share in 2023

3.2.3 Top 6 Packaging Materials for IGBT and SiC Modules Players Market Share in 2023

3.3 Packaging Materials for IGBT and SiC Modules Market: Overall Company Footprint Analysis

3.3.1 Packaging Materials for IGBT and SiC Modules Market: Region Footprint

3.3.2 Packaging Materials for IGBT and SiC Modules Market: Company Product Type Footprint

3.3.3 Packaging Materials for IGBT and SiC Modules Market: Company Product Application Footprint

3.4 New Market Entrants and Barriers to Market Entry

3.5 Mergers, Acquisition, Agreements, and Collaborations

# 4 MARKET SIZE SEGMENT BY TYPE

4.1 Global Packaging Materials for IGBT and SiC Modules Consumption Value and Market Share by Type (2019-2024)

4.2 Global Packaging Materials for IGBT and SiC Modules Market Forecast by Type (2025-2030)

# **5 MARKET SIZE SEGMENT BY APPLICATION**

5.1 Global Packaging Materials for IGBT and SiC Modules Consumption Value Market Share by Application (2019-2024)

5.2 Global Packaging Materials for IGBT and SiC Modules Market Forecast by Application (2025-2030)

# 6 NORTH AMERICA

6.1 North America Packaging Materials for IGBT and SiC Modules Consumption Value by Type (2019-2030)

6.2 North America Packaging Materials for IGBT and SiC Modules Market Size by Application (2019-2030)

6.3 North America Packaging Materials for IGBT and SiC Modules Market Size by Country

6.3.1 North America Packaging Materials for IGBT and SiC Modules Consumption Value by Country (2019-2030)



6.3.2 United States Packaging Materials for IGBT and SiC Modules Market Size and Forecast (2019-2030)

6.3.3 Canada Packaging Materials for IGBT and SiC Modules Market Size and Forecast (2019-2030)

6.3.4 Mexico Packaging Materials for IGBT and SiC Modules Market Size and Forecast (2019-2030)

# 7 EUROPE

7.1 Europe Packaging Materials for IGBT and SiC Modules Consumption Value by Type (2019-2030)

7.2 Europe Packaging Materials for IGBT and SiC Modules Consumption Value by Application (2019-2030)

7.3 Europe Packaging Materials for IGBT and SiC Modules Market Size by Country

7.3.1 Europe Packaging Materials for IGBT and SiC Modules Consumption Value by Country (2019-2030)

7.3.2 Germany Packaging Materials for IGBT and SiC Modules Market Size and Forecast (2019-2030)

7.3.3 France Packaging Materials for IGBT and SiC Modules Market Size and Forecast (2019-2030)

7.3.4 United Kingdom Packaging Materials for IGBT and SiC Modules Market Size and Forecast (2019-2030)

7.3.5 Russia Packaging Materials for IGBT and SiC Modules Market Size and Forecast (2019-2030)

7.3.6 Italy Packaging Materials for IGBT and SiC Modules Market Size and Forecast (2019-2030)

# 8 ASIA-PACIFIC

8.1 Asia-Pacific Packaging Materials for IGBT and SiC Modules Consumption Value by Type (2019-2030)

8.2 Asia-Pacific Packaging Materials for IGBT and SiC Modules Consumption Value by Application (2019-2030)

8.3 Asia-Pacific Packaging Materials for IGBT and SiC Modules Market Size by Region

8.3.1 Asia-Pacific Packaging Materials for IGBT and SiC Modules Consumption Value by Region (2019-2030)

8.3.2 China Packaging Materials for IGBT and SiC Modules Market Size and Forecast (2019-2030)

8.3.3 Japan Packaging Materials for IGBT and SiC Modules Market Size and Forecast



(2019-2030)

8.3.4 South Korea Packaging Materials for IGBT and SiC Modules Market Size and Forecast (2019-2030)

8.3.5 India Packaging Materials for IGBT and SiC Modules Market Size and Forecast (2019-2030)

8.3.6 Southeast Asia Packaging Materials for IGBT and SiC Modules Market Size and Forecast (2019-2030)

8.3.7 Australia Packaging Materials for IGBT and SiC Modules Market Size and Forecast (2019-2030)

# 9 SOUTH AMERICA

9.1 South America Packaging Materials for IGBT and SiC Modules Consumption Value by Type (2019-2030)

9.2 South America Packaging Materials for IGBT and SiC Modules Consumption Value by Application (2019-2030)

9.3 South America Packaging Materials for IGBT and SiC Modules Market Size by Country

9.3.1 South America Packaging Materials for IGBT and SiC Modules Consumption Value by Country (2019-2030)

9.3.2 Brazil Packaging Materials for IGBT and SiC Modules Market Size and Forecast (2019-2030)

9.3.3 Argentina Packaging Materials for IGBT and SiC Modules Market Size and Forecast (2019-2030)

# **10 MIDDLE EAST & AFRICA**

10.1 Middle East & Africa Packaging Materials for IGBT and SiC Modules Consumption Value by Type (2019-2030)

10.2 Middle East & Africa Packaging Materials for IGBT and SiC Modules Consumption Value by Application (2019-2030)

10.3 Middle East & Africa Packaging Materials for IGBT and SiC Modules Market Size by Country

10.3.1 Middle East & Africa Packaging Materials for IGBT and SiC Modules Consumption Value by Country (2019-2030)

10.3.2 Turkey Packaging Materials for IGBT and SiC Modules Market Size and Forecast (2019-2030)

10.3.3 Saudi Arabia Packaging Materials for IGBT and SiC Modules Market Size and Forecast (2019-2030)



10.3.4 UAE Packaging Materials for IGBT and SiC Modules Market Size and Forecast (2019-2030)

#### **11 MARKET DYNAMICS**

- 11.1 Packaging Materials for IGBT and SiC Modules Market Drivers
- 11.2 Packaging Materials for IGBT and SiC Modules Market Restraints
- 11.3 Packaging Materials for IGBT and SiC Modules Trends Analysis
- 11.4 Porters Five Forces Analysis
- 11.4.1 Threat of New Entrants
- 11.4.2 Bargaining Power of Suppliers
- 11.4.3 Bargaining Power of Buyers
- 11.4.4 Threat of Substitutes
- 11.4.5 Competitive Rivalry

### **12 INDUSTRY CHAIN ANALYSIS**

- 12.1 Packaging Materials for IGBT and SiC Modules Industry Chain
- 12.2 Packaging Materials for IGBT and SiC Modules Upstream Analysis
- 12.3 Packaging Materials for IGBT and SiC Modules Midstream Analysis
- 12.4 Packaging Materials for IGBT and SiC Modules Downstream Analysis

#### **13 RESEARCH FINDINGS AND CONCLUSION**

#### **14 APPENDIX**

- 14.1 Methodology
- 14.2 Research Process and Data Source
- 14.3 Disclaimer



# List Of Tables

### LIST OF TABLES

Table 1. Global Packaging Materials for IGBT and SiC Modules Consumption Value by Type, (USD Million), 2019 & 2023 & 2030

Table 2. Global Packaging Materials for IGBT and SiC Modules Consumption Value by Application, (USD Million), 2019 & 2023 & 2030

Table 3. Global Packaging Materials for IGBT and SiC Modules Consumption Value by Region (2019-2024) & (USD Million)

Table 4. Global Packaging Materials for IGBT and SiC Modules Consumption Value by Region (2025-2030) & (USD Million)

Table 5. Rogers Corporation Company Information, Head Office, and Major CompetitorsTable 6. Rogers Corporation Major Business

Table 7. Rogers Corporation Packaging Materials for IGBT and SiC Modules Product and Solutions

Table 8. Rogers Corporation Packaging Materials for IGBT and SiC Modules Revenue (USD Million), Gross Margin and Market Share (2019-2024)

 Table 9. Rogers Corporation Recent Developments and Future Plans

Table 10. MacDermid Alpha Company Information, Head Office, and Major Competitors

Table 11. MacDermid Alpha Major Business

Table 12. MacDermid Alpha Packaging Materials for IGBT and SiC Modules Product and Solutions

Table 13. MacDermid Alpha Packaging Materials for IGBT and SiC Modules Revenue (USD Million), Gross Margin and Market Share (2019-2024)

Table 14. MacDermid Alpha Recent Developments and Future Plans

Table 15. 3M Company Information, Head Office, and Major Competitors

Table 16. 3M Major Business

Table 17. 3M Packaging Materials for IGBT and SiC Modules Product and Solutions

Table 18. 3M Packaging Materials for IGBT and SiC Modules Revenue (USD Million), Gross Margin and Market Share (2019-2024)

Table 19. Dow Company Information, Head Office, and Major Competitors

Table 20. Dow Major Business

Table 21. Dow Packaging Materials for IGBT and SiC Modules Product and Solutions

Table 22. Dow Packaging Materials for IGBT and SiC Modules Revenue (USD Million),

Gross Margin and Market Share (2019-2024)

Table 23. Dow Recent Developments and Future Plans

Table 24. Indium Corporation Company Information, Head Office, and Major Competitors

Global Packaging Materials for IGBT and SiC Modules Market 2024 by Company, Regions, Type and Application, For...



Table 25. Indium Corporation Major Business

Table 26. Indium Corporation Packaging Materials for IGBT and SiC Modules Product and Solutions

Table 27. Indium Corporation Packaging Materials for IGBT and SiC Modules Revenue (USD Million), Gross Margin and Market Share (2019-2024)

Table 28. Indium Corporation Recent Developments and Future Plans

Table 29. Heraeus Company Information, Head Office, and Major Competitors

Table 30. Heraeus Major Business

Table 31. Heraeus Packaging Materials for IGBT and SiC Modules Product and Solutions

Table 32. Heraeus Packaging Materials for IGBT and SiC Modules Revenue (USD Million), Gross Margin and Market Share (2019-2024)

Table 33. Heraeus Recent Developments and Future Plans

Table 34. Henkel Company Information, Head Office, and Major Competitors

Table 35. Henkel Major Business

Table 36. Henkel Packaging Materials for IGBT and SiC Modules Product and Solutions

Table 37. Henkel Packaging Materials for IGBT and SiC Modules Revenue (USD

Million), Gross Margin and Market Share (2019-2024)

- Table 38. Henkel Recent Developments and Future Plans
- Table 39. Ferrotec Company Information, Head Office, and Major Competitors
- Table 40. Ferrotec Major Business

Table 41. Ferrotec Packaging Materials for IGBT and SiC Modules Product and Solutions

Table 42. Ferrotec Packaging Materials for IGBT and SiC Modules Revenue (USD Million), Gross Margin and Market Share (2019-2024)

- Table 43. Ferrotec Recent Developments and Future Plans
- Table 44. Kyocera Company Information, Head Office, and Major Competitors
- Table 45. Kyocera Major Business

Table 46. Kyocera Packaging Materials for IGBT and SiC Modules Product and Solutions

Table 47. Kyocera Packaging Materials for IGBT and SiC Modules Revenue (USD Million), Gross Margin and Market Share (2019-2024)

Table 48. Kyocera Recent Developments and Future Plans

Table 49. NGK Electronics Devices Company Information, Head Office, and Major Competitors

Table 50. NGK Electronics Devices Major Business

Table 51. NGK Electronics Devices Packaging Materials for IGBT and SiC Modules Product and Solutions

Table 52. NGK Electronics Devices Packaging Materials for IGBT and SiC Modules



Revenue (USD Million), Gross Margin and Market Share (2019-2024) Table 53. NGK Electronics Devices Recent Developments and Future Plans Table 54. Dowa Company Information, Head Office, and Major Competitors Table 55. Dowa Major Business Table 56. Dowa Packaging Materials for IGBT and SiC Modules Product and Solutions Table 57. Dowa Packaging Materials for IGBT and SiC Modules Revenue (USD Million), Gross Margin and Market Share (2019-2024) Table 58. Dowa Recent Developments and Future Plans Table 59. Denka Company Information, Head Office, and Major Competitors Table 60. Denka Major Business Table 61. Denka Packaging Materials for IGBT and SiC Modules Product and Solutions Table 62. Denka Packaging Materials for IGBT and SiC Modules Revenue (USD Million), Gross Margin and Market Share (2019-2024) Table 63. Denka Recent Developments and Future Plans Table 64. Tanaka Company Information, Head Office, and Major Competitors Table 65. Tanaka Major Business Table 66. Tanaka Packaging Materials for IGBT and SiC Modules Product and Solutions Table 67. Tanaka Packaging Materials for IGBT and SiC Modules Revenue (USD Million), Gross Margin and Market Share (2019-2024) Table 68. Tanaka Recent Developments and Future Plans Table 69. Resonac Company Information, Head Office, and Major Competitors Table 70. Resonac Major Business Table 71. Resonac Packaging Materials for IGBT and SiC Modules Product and Solutions Table 72. Resonac Packaging Materials for IGBT and SiC Modules Revenue (USD Million), Gross Margin and Market Share (2019-2024) Table 73. Resonac Recent Developments and Future Plans Table 74. BYD Company Information, Head Office, and Major Competitors Table 75. BYD Major Business Table 76. BYD Packaging Materials for IGBT and SiC Modules Product and Solutions Table 77. BYD Packaging Materials for IGBT and SiC Modules Revenue (USD Million), Gross Margin and Market Share (2019-2024) Table 78. BYD Recent Developments and Future Plans Table 79. Toshiba Materials Company Information, Head Office, and Major Competitors Table 80. Toshiba Materials Major Business Table 81. Toshiba Materials Packaging Materials for IGBT and SiC Modules Product and Solutions

Table 82. Toshiba Materials Packaging Materials for IGBT and SiC Modules Revenue



(USD Million), Gross Margin and Market Share (2019-2024) Table 83. Toshiba Materials Recent Developments and Future Plans Table 84. KCC Company Information, Head Office, and Major Competitors Table 85. KCC Major Business Table 86. KCC Packaging Materials for IGBT and SiC Modules Product and Solutions Table 87. KCC Packaging Materials for IGBT and SiC Modules Revenue (USD Million), Gross Margin and Market Share (2019-2024) Table 88. KCC Recent Developments and Future Plans Table 89. Shengda Tech Company Information, Head Office, and Major Competitors Table 90. Shengda Tech Major Business Table 91. Shengda Tech Packaging Materials for IGBT and SiC Modules Product and Solutions Table 92. Shengda Tech Packaging Materials for IGBT and SiC Modules Revenue (USD Million), Gross Margin and Market Share (2019-2024) Table 93. Shengda Tech Recent Developments and Future Plans Table 94. Nanjing Zhongjiang New Material Science & Technology Company Information, Head Office, and Major Competitors Table 95. Nanjing Zhongjiang New Material Science & Technology Major Business Table 96. Nanjing Zhongjiang New Material Science & Technology Packaging Materials for IGBT and SiC Modules Product and Solutions Table 97. Nanjing Zhongjiang New Material Science & Technology Packaging Materials for IGBT and SiC Modules Revenue (USD Million), Gross Margin and Market Share (2019-2024)Table 98. Nanjing Zhongjiang New Material Science & Technology Recent **Developments and Future Plans** Table 99. Global Packaging Materials for IGBT and SiC Modules Revenue (USD Million) by Players (2019-2024) Table 100. Global Packaging Materials for IGBT and SiC Modules Revenue Share by Players (2019-2024) Table 101. Breakdown of Packaging Materials for IGBT and SiC Modules by Company Type (Tier 1, Tier 2, and Tier 3) Table 102. Market Position of Players in Packaging Materials for IGBT and SiC Modules, (Tier 1, Tier 2, and Tier 3), Based on Revenue in 2023

Table 103. Head Office of Key Packaging Materials for IGBT and SiC Modules Players Table 104. Packaging Materials for IGBT and SiC Modules Market: Company Product Type Footprint

Table 105. Packaging Materials for IGBT and SiC Modules Market: Company ProductApplication Footprint

Table 106. Packaging Materials for IGBT and SiC Modules New Market Entrants and



Barriers to Market Entry

Table 107. Packaging Materials for IGBT and SiC Modules Mergers, Acquisition,

Agreements, and Collaborations

Table 108. Global Packaging Materials for IGBT and SiC Modules Consumption Value (USD Million) by Type (2019-2024)

Table 109. Global Packaging Materials for IGBT and SiC Modules Consumption Value Share by Type (2019-2024)

Table 110. Global Packaging Materials for IGBT and SiC Modules Consumption Value Forecast by Type (2025-2030)

Table 111. Global Packaging Materials for IGBT and SiC Modules Consumption Value by Application (2019-2024)

Table 112. Global Packaging Materials for IGBT and SiC Modules Consumption Value Forecast by Application (2025-2030)

Table 113. North America Packaging Materials for IGBT and SiC Modules Consumption Value by Type (2019-2024) & (USD Million)

Table 114. North America Packaging Materials for IGBT and SiC Modules Consumption Value by Type (2025-2030) & (USD Million)

Table 115. North America Packaging Materials for IGBT and SiC Modules Consumption Value by Application (2019-2024) & (USD Million)

Table 116. North America Packaging Materials for IGBT and SiC Modules Consumption Value by Application (2025-2030) & (USD Million)

Table 117. North America Packaging Materials for IGBT and SiC Modules Consumption Value by Country (2019-2024) & (USD Million)

Table 118. North America Packaging Materials for IGBT and SiC Modules Consumption Value by Country (2025-2030) & (USD Million)

Table 119. Europe Packaging Materials for IGBT and SiC Modules Consumption Value by Type (2019-2024) & (USD Million)

Table 120. Europe Packaging Materials for IGBT and SiC Modules Consumption Value by Type (2025-2030) & (USD Million)

Table 121. Europe Packaging Materials for IGBT and SiC Modules Consumption Value by Application (2019-2024) & (USD Million)

Table 122. Europe Packaging Materials for IGBT and SiC Modules Consumption Value by Application (2025-2030) & (USD Million)

Table 123. Europe Packaging Materials for IGBT and SiC Modules Consumption Value by Country (2019-2024) & (USD Million)

Table 124. Europe Packaging Materials for IGBT and SiC Modules Consumption Value by Country (2025-2030) & (USD Million)

Table 125. Asia-Pacific Packaging Materials for IGBT and SiC Modules Consumption Value by Type (2019-2024) & (USD Million)



Table 126. Asia-Pacific Packaging Materials for IGBT and SiC Modules Consumption Value by Type (2025-2030) & (USD Million)

Table 127. Asia-Pacific Packaging Materials for IGBT and SiC Modules Consumption Value by Application (2019-2024) & (USD Million)

Table 128. Asia-Pacific Packaging Materials for IGBT and SiC Modules Consumption Value by Application (2025-2030) & (USD Million)

Table 129. Asia-Pacific Packaging Materials for IGBT and SiC Modules Consumption Value by Region (2019-2024) & (USD Million)

Table 130. Asia-Pacific Packaging Materials for IGBT and SiC Modules Consumption Value by Region (2025-2030) & (USD Million)

Table 131. South America Packaging Materials for IGBT and SiC Modules Consumption Value by Type (2019-2024) & (USD Million)

Table 132. South America Packaging Materials for IGBT and SiC Modules Consumption Value by Type (2025-2030) & (USD Million)

Table 133. South America Packaging Materials for IGBT and SiC Modules Consumption Value by Application (2019-2024) & (USD Million)

Table 134. South America Packaging Materials for IGBT and SiC Modules Consumption Value by Application (2025-2030) & (USD Million)

Table 135. South America Packaging Materials for IGBT and SiC Modules Consumption Value by Country (2019-2024) & (USD Million)

Table 136. South America Packaging Materials for IGBT and SiC Modules Consumption Value by Country (2025-2030) & (USD Million)

Table 137. Middle East & Africa Packaging Materials for IGBT and SiC Modules Consumption Value by Type (2019-2024) & (USD Million)

Table 138. Middle East & Africa Packaging Materials for IGBT and SiC Modules Consumption Value by Type (2025-2030) & (USD Million)

Table 139. Middle East & Africa Packaging Materials for IGBT and SiC Modules Consumption Value by Application (2019-2024) & (USD Million)

Table 140. Middle East & Africa Packaging Materials for IGBT and SiC Modules Consumption Value by Application (2025-2030) & (USD Million)

Table 141. Middle East & Africa Packaging Materials for IGBT and SiC Modules Consumption Value by Country (2019-2024) & (USD Million)

Table 142. Middle East & Africa Packaging Materials for IGBT and SiC Modules Consumption Value by Country (2025-2030) & (USD Million)

Table 143. Global Key Players of Packaging Materials for IGBT and SiC Modules Upstream (Raw Materials)

Table 144. Global Packaging Materials for IGBT and SiC Modules Typical Customers



# **List Of Figures**

#### LIST OF FIGURES

Figure 1. Packaging Materials for IGBT and SiC Modules Picture

Figure 2. Global Packaging Materials for IGBT and SiC Modules Consumption Value by

Type, (USD Million), 2019 & 2023 & 2030

Figure 3. Global Packaging Materials for IGBT and SiC Modules Consumption Value

Market Share by Type in 2023

Figure 4. Encapsulation (Silicone Gel and Epoxy)

Figure 5. ????

Figure 6. Ceramic Substrate

Figure 7. Thermal Interface Materials

Figure 8. Electrical Interconnection

Figure 9. Others

Figure 10. Global Packaging Materials for IGBT and SiC Modules Consumption Value by Application, (USD Million), 2019 & 2023 & 2030

Figure 11. Packaging Materials for IGBT and SiC Modules Consumption Value Market

Share by Application in 2023

Figure 12. Automotive Picture

- Figure 13. Traction & Railway Picture
- Figure 14. PV, Wind Power & Power Grid Picture
- Figure 15. Industrial Motor Picture
- Figure 16. Home Appliances Picture
- Figure 17. USP Picture

Figure 18. Other Picture

Figure 19. Global Packaging Materials for IGBT and SiC Modules Consumption Value, (USD Million): 2019 & 2023 & 2030

Figure 20. Global Packaging Materials for IGBT and SiC Modules Consumption Value and Forecast (2019-2030) & (USD Million)

Figure 21. Global Market Packaging Materials for IGBT and SiC Modules Consumption Value (USD Million) Comparison by Region (2019 VS 2023 VS 2030)

Figure 22. Global Packaging Materials for IGBT and SiC Modules Consumption Value Market Share by Region (2019-2030)

Figure 23. Global Packaging Materials for IGBT and SiC Modules Consumption Value Market Share by Region in 2023

Figure 24. North America Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 25. Europe Packaging Materials for IGBT and SiC Modules Consumption Value



(2019-2030) & (USD Million)

Figure 26. Asia-Pacific Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 27. South America Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 28. Middle East & Africa Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 29. Company Three Recent Developments and Future Plans

Figure 30. Global Packaging Materials for IGBT and SiC Modules Revenue Share by Players in 2023

Figure 31. Packaging Materials for IGBT and SiC Modules Market Share by Company Type (Tier 1, Tier 2, and Tier 3) in 2023

Figure 32. Market Share of Packaging Materials for IGBT and SiC Modules by Player Revenue in 2023

Figure 33. Top 3 Packaging Materials for IGBT and SiC Modules Players Market Share in 2023

Figure 34. Top 6 Packaging Materials for IGBT and SiC Modules Players Market Share in 2023

Figure 35. Global Packaging Materials for IGBT and SiC Modules Consumption Value Share by Type (2019-2024)

Figure 36. Global Packaging Materials for IGBT and SiC Modules Market Share Forecast by Type (2025-2030)

Figure 37. Global Packaging Materials for IGBT and SiC Modules Consumption Value Share by Application (2019-2024)

Figure 38. Global Packaging Materials for IGBT and SiC Modules Market Share Forecast by Application (2025-2030)

Figure 39. North America Packaging Materials for IGBT and SiC Modules Consumption Value Market Share by Type (2019-2030)

Figure 40. North America Packaging Materials for IGBT and SiC Modules Consumption Value Market Share by Application (2019-2030)

Figure 41. North America Packaging Materials for IGBT and SiC Modules Consumption Value Market Share by Country (2019-2030)

Figure 42. United States Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 43. Canada Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 44. Mexico Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 45. Europe Packaging Materials for IGBT and SiC Modules Consumption Value,



Market Share by Type (2019-2030)

Figure 46. Europe Packaging Materials for IGBT and SiC Modules Consumption Value Market Share by Application (2019-2030)

Figure 47. Europe Packaging Materials for IGBT and SiC Modules Consumption Value Market Share by Country (2019-2030)

Figure 48. Germany Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 49. France Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 50. United Kingdom Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 51. Russia Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 52. Italy Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 53. Asia-Pacific Packaging Materials for IGBT and SiC Modules Consumption Value Market Share by Type (2019-2030)

Figure 54. Asia-Pacific Packaging Materials for IGBT and SiC Modules Consumption Value Market Share by Application (2019-2030)

Figure 55. Asia-Pacific Packaging Materials for IGBT and SiC Modules Consumption Value Market Share by Region (2019-2030)

Figure 56. China Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 57. Japan Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 58. South Korea Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 59. India Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 60. Southeast Asia Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 61. Australia Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 62. South America Packaging Materials for IGBT and SiC Modules Consumption Value Market Share by Type (2019-2030)

Figure 63. South America Packaging Materials for IGBT and SiC Modules Consumption Value Market Share by Application (2019-2030)

Figure 64. South America Packaging Materials for IGBT and SiC Modules Consumption Value Market Share by Country (2019-2030)



Figure 65. Brazil Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 66. Argentina Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 67. Middle East & Africa Packaging Materials for IGBT and SiC Modules Consumption Value Market Share by Type (2019-2030)

Figure 68. Middle East & Africa Packaging Materials for IGBT and SiC Modules Consumption Value Market Share by Application (2019-2030)

Figure 69. Middle East & Africa Packaging Materials for IGBT and SiC Modules Consumption Value Market Share by Country (2019-2030)

Figure 70. Turkey Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 71. Saudi Arabia Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 72. UAE Packaging Materials for IGBT and SiC Modules Consumption Value (2019-2030) & (USD Million)

Figure 73. Packaging Materials for IGBT and SiC Modules Market Drivers

Figure 74. Packaging Materials for IGBT and SiC Modules Market Restraints

- Figure 75. Packaging Materials for IGBT and SiC Modules Market Trends
- Figure 76. Porters Five Forces Analysis

Figure 77. Packaging Materials for IGBT and SiC Modules Industrial Chain

- Figure 78. Methodology
- Figure 79. Research Process and Data Source



#### I would like to order

 Product name: Global Packaging Materials for IGBT and SiC Modules Market 2024 by Company, Regions, Type and Application, Forecast to 2030
 Product link: <u>https://marketpublishers.com/r/G93D239D5273EN.html</u>
 Price: US\$ 3,480.00 (Single User License / Electronic Delivery)
 If you want to order Corporate License or Hard Copy, please, contact our Customer Service: info@marketpublishers.com

### Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <u>https://marketpublishers.com/r/G93D239D5273EN.html</u>

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name: Last name: Email: Company: Address: City: Zip code: Country: Tel: Fax: Your message:

\*\*All fields are required

Custumer signature \_\_\_\_\_

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at <u>https://marketpublishers.com/docs/terms.html</u>

To place an order via fax simply print this form, fill in the information below and fax the completed form to +44 20 7900 3970



Global Packaging Materials for IGBT and SiC Modules Market 2024 by Company, Regions, Type and Application, For...